

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-25 (Canceled)

Claim 26 (Currently Amended): An electronic device comprising:  
an electronic part or die joined to a heat spreader joined to a heat sink,  
wherein said heat spreader comprises a sealed structure encapsulating a condensable fluid therein which can repeatedly evaporate and condense to transport heat; and  
wherein said electronic device comprises means for bonding or integrally joining the die or electronic part and the heat spreader so that thermal stress that causes separation of the die or electronic part and the heat spreader does not occur,  
wherein the die or electronic part and heat spreader components are selected to have about the same coefficients of thermal expansion such that they do not generate thermal stress sufficient to separate the die or electronic part and the heat spreader.

Claim 27 (Canceled)

Claims 28-31 (Canceled)

Claim 32 (Withdrawn): The electronic device of Claim 26, wherein the heat spreader has a lubricating material buried in one face.

Claim 33 (Withdrawn): The electronic device of Claim 26,  
wherein the heat spreader is made of aluminum and has an anodized face having fine cracks which are and filled with molybdenum sulfide as the lubricating material.

Claim 34 (Previously Presented): The electronic device of Claim 26, wherein said die or electronic part comprises silicon.

Claim 35 (Previously Presented): The electronic device of Claim 26, wherein said heat spreader is invar (nickel steel) which comprises 0.4% Mn, 0.2% C, 36% Ni, and the remainder Fe.

Claim 36 (Previously Presented): The electronic device of Claim 26, wherein said heat spreader is aluminum nitride.

Claim 37 (Previously Presented): The electronic device of Claim 26, which is an MPU.

Claim 38 (Previously Presented): The electronic device of Claim 26, which is an image processor.

Claim 39 (Currently Amended): An electronic device comprising:  
an electronic part or die, which is bonded or integrally joined to a heat spreader which is joined to a heat sink,

wherein said heat spreader comprises a sealed structure encapsulating a condensable fluid therein which can repeatedly evaporate and condense to transport heat; and

wherein the die or electronic part is soldered, soft soldered, bonded or integrally-joined by a synthetic resin adhesive, or bonded or integrally joined by a diffuse junction method, to the heat spreader so that thermal stress that causes separation of the die or electronic part and the heat spreader does not occur,

wherein the die or electronic part and heat spreader components are selected to have about the same coefficients of thermal expansion such that they do not generate significant thermal stress between the gradient layer and the die or electronic part or heat spreader.

Claim 40 (Cancelled)

Claim 41 (Withdrawn): The electronic device of Claim 40, wherein the electronic part or die is joined to the heat spreader via a grading layer which has three layers, wherein the layer in contact with the electronic part or die has a coefficient of thermal expansion approximate to that of the electronic part or die and the layer in contact with the heat spreader has a coefficient of thermal expansion approximate to that of the heat spreader, and these two layers are separated by an intermediate layer having a coefficient of thermal expansion between that of the electronic part or die and the heat spreader.

Claim 42 (Withdrawn): The electronic device of Claim 39, wherein the heat spreader has a lubricating material buried in one face.

Claire 43 (Withdrawn): The electronic device of Claim 39, wherein the heat spreader is made of aluminum and has an anodized face having fine cracks which are filled with molybdenum sulfide as the lubricating material.

Claim 44 (Previously Presented): The electronic device of Claim 39, wherein said die or electronic part comprises silicon.

Claim 45 (Previously Presented): The electronic device of Claim 39, wherein said heat spreader is invar (nickel steel) which comprises 0.4% Mn, 0.2% C, 36% Ni, and the remainder Fe.

Claim 46 (Previously Presented): The electronic device of Claim 39, wherein said heat spreader is aluminum nitride.

Claim 47 (Previously Presented): The electronic device of Claim 39, which is an MPU.

Claim 48 (Previously Presented): The electronic device of Claim 39, which is an image processor.

Claim 49 (Withdrawn): An electronic device comprising:  
an electronic part or die, which is integrally joined via a graphite layer to a heat spreader joined to a heat sink,  
wherein said heat spreader comprises a sealed structure encapsulating a condensable fluid therein which can repeatedly evaporate and condense to transport heat; and  
wherein the die or electronic part is bonded or integrally joined to the heat spreader so that thermal stress that causes separation of the die or electronic part and the heat spreader does not occur.